



Product Data Sheet

PA66 100L NC010

PA66 100L NC010 is a general purpose polyamide 66 resin for injection molding and extrusion.

Property	Test Method	Units	Value
			DAM
Mechanical			
Yield Stress	ISO 527-2	MPa (kpsi)	82 (11.9)
Strain @ break	ISO 527-2	%	40
Tensile Modulus	ISO 527-2	MPa (kpsi)	3100 (450)
Flexural Modulus	ISO 178	MPa (kpsi)	2800 (410)
Notched Charpy Impact Strength	ISO 179/1eA	kJ/m ²	-30 °C (-22 °F)
			23 °C (73 °F)
Thermal			
Heat Deflection Temperature 1.8 Mpa (264 psi)	ISO 75-2/A	°C (°F)	70 (158)
Melting Point	ISO 11357-3	°C (°F)	263 (505)
Physical			
Specific Gravity	ISO 1183	g/cm ³	1.14
Molding Shrinkage	ISO 294-4	%a	1.5 -3.0
Processing			
Melt Temperature Range		°C (°F)	280-300 (535 – 570)
Mold Temperature Range		°C (°F)	50-90 (120-190)
Processing Moisture Content		%	<0.20

Mechanical properties measured at 23°C (73°F)

Contact JEDA Polymers, LLC. for MSDS, general guidelines and/or additional information about ventilation, handling, purging, drying, etc.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. This information may be subject to revision as new knowledge and experience becomes available. The data provided fall within the normal range of product properties and relate only to specific material designated; these data may not be valid for such material used in combination with any other materials or additives or in any process, unless expressly indicated otherwise. The data provided should not be used to establish specification limits or used alone as the basis of design; they are not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of a specific material for your particular purposes. Since JEDA Polymers cannot anticipate all variations in actual end-use conditions JEDA Polymers makes no warranties and assumes no liability in connection with any use of this information. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent rights. Caution: Do not use this product in medical applications involving permanent implantation in the human body.